



## P-Channel 12 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)Max.$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
- 12	0.640 at V <sub>GS</sub> = - 4.5 V	- 0.48			
	0.880 at V <sub>GS</sub> = - 2.5 V	- 0.41			
	1.200 at V <sub>GS</sub> = - 1.8 V	- 0.35	1.15 nC		
	1.443 at V <sub>GS</sub> = - 1.5 V	- 0.10			
	2.475 at V <sub>GS</sub> = - 1.2 V	- 0.05			

#### **FEATURES**

- TrenchFET® Power MOSFET
- Typical ESD protection: 700 V (HBM)
- Fast Switching Speed
- Material categorization:

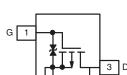
For definitions of compliance please see www.vishay.com/doc?99912





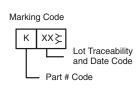
#### **APPLICATIONS**

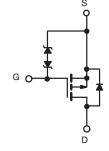
- Portable Devices such as Smart Phones, Tablet PCs and Mobile Computing
  - Load Switch for Low Voltage Gate Drive
  - Load Switch for 1.2 V Power Line



SC-89 (3-LEADS)







Ordering Information: Si1011X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 12	V	
Gate-Source Voltage		V <sub>GS</sub>	± 5	v	
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>A</sub> = 25 °C		- 0.48 <sup>b, c</sup>		
Continuous Diam Current (1) = 130 °C)	T <sub>A</sub> = 70 °C	l I <sub>D</sub>	- 0.38 <sup>b, c</sup>	A	
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	- 1.5	^	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub> - 0.16 <sup>b, c</sup>		1	
Maximum Davier Dissination	T <sub>A</sub> = 25 °C	В	0.19 <sup>b, c</sup>	W	
Maximum Power Dissipation	T <sub>A</sub> = 70 °C	P <sub>D</sub>	0.12 <sup>b, c</sup>	vv	
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Manifestory London Landa Ambienta A	t ≤ 5 s	B	440	530	°C/W		
Maximum Junction-to-Ambient <sup>a, b</sup>	Steady State	$R_{thJA}$	540	650			

- a. Maximum under steady state conditions is 650 °C/W.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.

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<b>SPECIFICATIONS</b> $(T_J = 25^{\circ})$	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	cyze.	Tool Conditions		.,,,,	iii daa		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0, I <sub>D</sub> = - 250 μA	- 12			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Τ,		- 7			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		1.7		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.35		- 0.8	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$			± 10	<u> </u>	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1	- - μA	
	I <sub>DSS</sub>	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current		$V_{DS}$ = - 12 V, $V_{GS}$ = 0 V, $T_{J}$ = 85 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 V$ , $V_{GS} = -4.5 V$	- 1.5			Α	
	,	$V_{GS} = -4.5 \text{ V}, I_D = -0.4 \text{ A}$		0.530	0.640		
		$V_{GS} = -2.5 \text{ V}, I_D = -0.2 \text{ A}$		0.730	0.880	1	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.1 A		0.920	1.200	Ω	
	-(* /	V <sub>GS</sub> = - 1.5 V, I <sub>D</sub> = - 0.05 A		1.100	1.443		
		V <sub>GS</sub> = - 1.2 V, I <sub>D</sub> = - 0.05 A		1.650	2.475	1	
Forward Transconductance	9 <sub>fs</sub>	$V_{DS} = -6 \text{ V}, I_D = -0.4 \text{ A}$		1		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			62		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		26			
Reverse Transfer Capacitance	C <sub>rss</sub>			20			
Total Cata Charga	Q <sub>g</sub> -	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.4 \text{ A}$		2	4	nC	
Total Gate Charge		V <sub>DS</sub> = -6 V, V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -0.4 A		1.15	2		
Gate-Source Charge				0.37			
Gate-Drain Charge	$Q_{\mathrm{gd}}$			0.43			
Gate Resistance	$R_{g}$	f = 1 MHz		12		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			4	8		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 6 V, $R_L$ = 20 $\Omega$		11	20	ns	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 0.3 A, $V_{GEN}$ = - 5 V, $R_g$ = 1 $\Omega$		9	18	_	
Fall Time	t <sub>f</sub>			9	18		
Drain-Source Body Diode Characteris	tics					1	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 1.5	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 0.3 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			12	20	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = - 0.3 A, dl/dt = 100 A/μs		5	10	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	17 - 0.07., and - 10070po		7		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			5			

#### Notes:

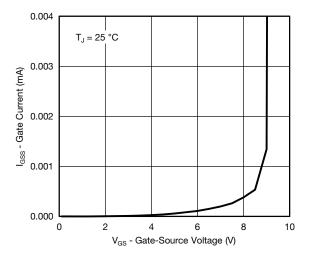
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

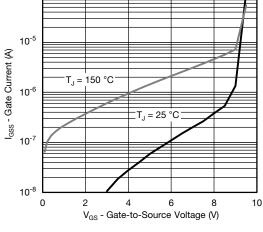
b. Guaranteed by design, not subject to production testing.



#### P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

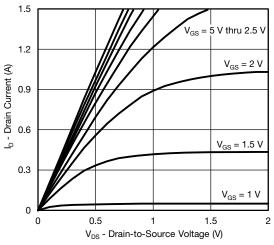


#### Gate Current vs. Gate-Source Voltage

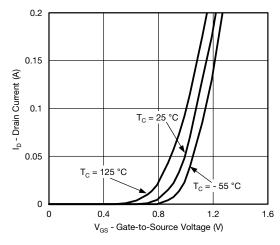


10<sup>-4</sup>

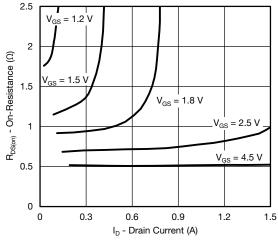
Gate Current vs. Gate-Source Voltage



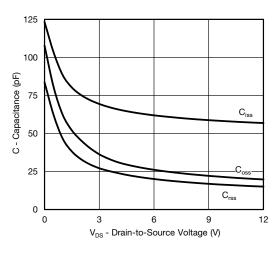
**Output Characteristics** 



**Transfer Characteristics** 



On-Resistance vs. Drain Current

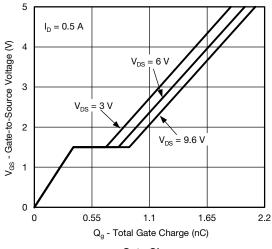


Capacitance

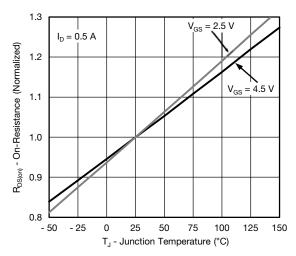
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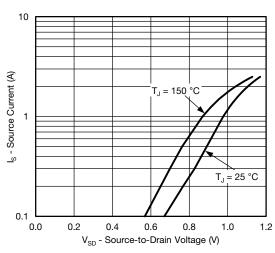
#### P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



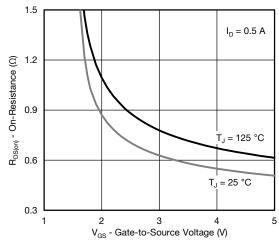




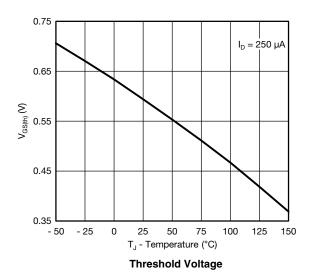
On-Resistance vs. Junction Temperature

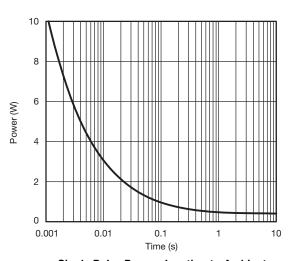


Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

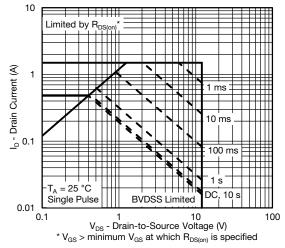


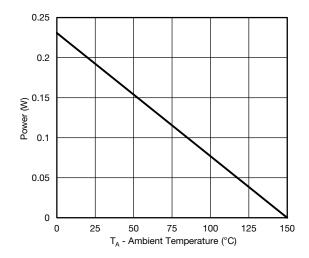


Single Pulse Power, Junction-to-Ambient



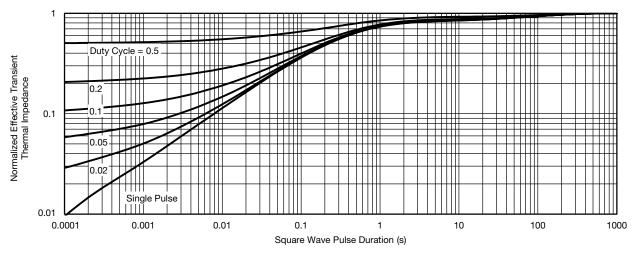
#### P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

Power Derating, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

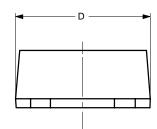
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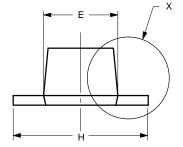


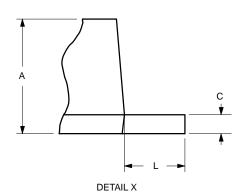


# Vishay Siliconix

#### SC89-3





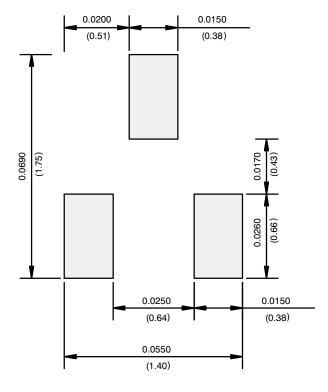


**MILLIMETERS INCHES** Dim Min Max Min Max 0.60 0.80 0.024 0.031 Α 0.23 0.33 0.009 0.013 b С 0.10 0.20 0.004 0.008 1.50 0.067 D 1.70 0.059 Ε 0.75 0.95 0.030 0.037 1.00 BSC 0.040 BSC е 0.50 BSC 0.020 BSC e<sub>1</sub> Н 1.50 0.059 0.067 0.30 0.012 0.020 L 0.50

ECN: S-03946—Rev. B, 09-Jul-01 DWG: 5869



#### **RECOMMENDED MINIMUM PADS FOR SC-89: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

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Revision: 02-Oct-12 Document Number: 91000

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IPS70R2K0CEAKMA1 BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI

DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384

NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956

NTE2911 US6M2GTR TK10A80W,S4X(S SSM6P69NU,LF